GSM2265JRF

20V Dual P-Channel Enhancement Mode MOSFET

Product Description

The P-Channel enhancement mode power field effect transistor is using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

This device is well suited for high efficiency fast switching applications.

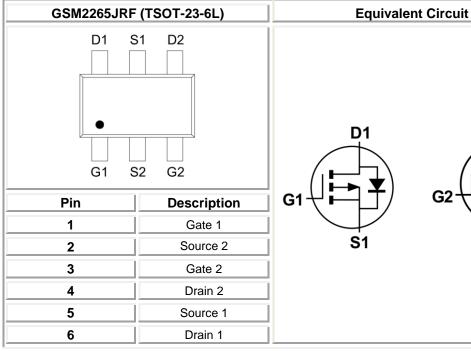
Features

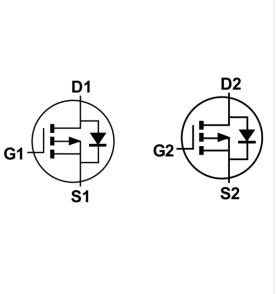
- $R_{DS(ON)}=65m\Omega@V_{GS}=-4.5V$
- $R_{DS(ON)}=85m\Omega@V_{GS}=-2.5V$
- $R_{DS(ON)}=130m\Omega@V_{GS}=-1.8V$
- Improved dv/dt capability
- Fast switching
- Suit for -1.8V Gate Drive Applications
- TSOT-23-6L package design

Applications

- Notebook
- Load Switch
- Hand-held Instruments

Packages & Pin Assignments







Ordering and Marking Information

Ordering Information				
Part Number	Package Part Marking Quantity		Quantity / Reel	
GSM2265JRF	TSOT-23-6L	P1	3,000 PCS	
GSM2265 1 2 - Product Code: GSM2265	luct Code: - Package Code: - Green Level:			
	Marking In	formation		
P1	- Product Cod P1 - GS Code: □□	e:		

Absolute Maximum Ratings

T_A=25°C, unless otherwise specified

Symbol	Parameter		Value	Unit
V _{DSS}	Drain-Source Voltage		-20	V
Vgss	Gate-Source Voltage		±12	V
	Continuous Busin Comment	T _A =25°C	-3.7	A
lσ	Continuous Drain Current	T _A =70°C	-2.9	
Ірм	Pulsed Drain Current ¹		-14	Α
_	Total Power Dissipation	T _A =25°C	1.25	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\
PD		T _A =70°C	0.8	W
TJ	Operating Junction Temperature Range		-55 to +150	°C
Tstg	Storage Temperature Range		-55 to +150	°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		100	°C/W

Note

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.



Electrical Characteristics

T_A=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
	Static 6	characteristics				
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250µA	-20	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250µA	-0.4	-	-0.9	V
I _{GSS}	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-20V, V _{GS} =0V	-	-	-1	μΑ
	Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-4.5A	-	52	65	
R _{DS(ON)}		V _{GS} =-2.5V, I _D =-3A	-	72	85	mΩ
		V _{GS} =-1.8V, I _D =-1.5A	-	100	130	
g FS	Forward Transconductance	V _{DS} =-5V, I _D =-4.5A	-	11	-	S
V_{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-1A		-0.8	-1.2	V
	Dynami	c characteristics				
Ciss	Input Capacitance		-	515	-	pF
Coss	Output Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1MHz	-	55	-	
Crss	Reverse Transfer Capacitance	1-11/11/12	-	20	-	
Q_g	Total Gate Charge ^{2,3}		-	6.4	-	
Qgs	Gate-Source Charge ^{2,3}	V _{DS} =-10V, V _{GS} =-4.5V, I _D =-3A	-	0.9	-	nC
Q _{gd}	Gate-Drain Charge ^{2,3}		-	1.6	-	
t _{d(on)}	Turn-On Delay Time ^{2,3}		-	5	-	
tr	Turn-On Rise Time ^{2,3}	V _{DD} =-10V, I _D =-1A,	-	17.4	-	
t _{d(off)}	Turn-Off Delay Time ^{2,3}	V_{GS} =-4.5V, R_{G} =25 Ω	-	40.7	-	ns
t _f	Turn-Off Fall Time ^{2,3}		-	11.4	-	

Note:

- 2. The data tested by pulsed, pulse width \leq 300us, duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.



Typical Performance Characteristics

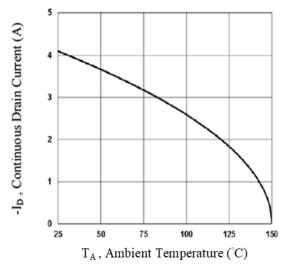


Fig.1 Continuous Drain Current vs T_{A}

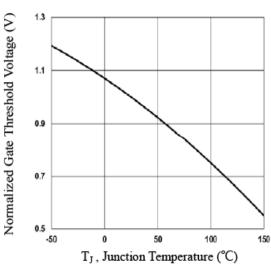


Fig.3 Normalized $V_{\text{GS(th)}}$ vs T_J

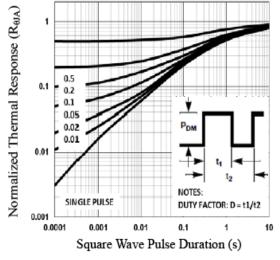


Fig.5 Normalized Transient Impedance

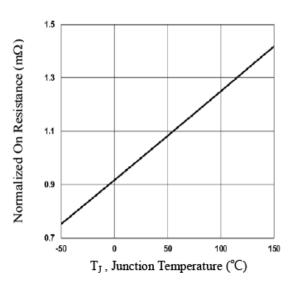


Fig.2 Normalized $R_{\text{DS}(\text{ON})} \, \text{vs} \, T_{\text{J}}$

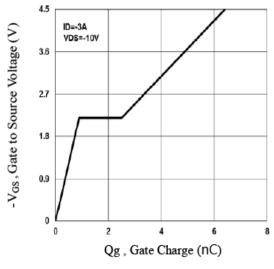


Fig.4 Gate Charge

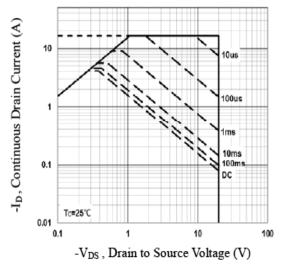
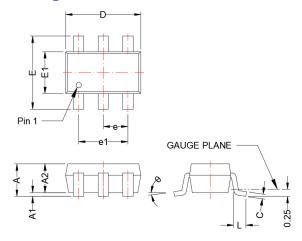


Fig.8 Maximum Safe Operating Area

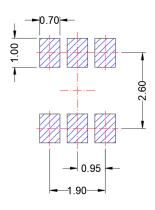


TSOT-23-6L

Package Dimension



Recommended Land Pattern



	Dimensions				
0	Millimeters		Inches		
Symbol	MIN	MAX	MIN	MAX	
Α	-	1.10	-	0.043	
A 1	0.00	0.10	0.000	0.004	
A2	0.70	1.00	0.028	0.039	
b	0.30	0.50	0.012	0.020	
С	0.08	0.20	0.003	0.008	
D	2.70	3.10	0.106	0.122	
E	2.20	3.00	0.087	0.118	
E1	1.30	1.75	0.051	0.069	
е	0.95 BSC		0.037 BSC		
e1	1.90 BSC		0.075 BSC		
L	0.3	0.6	0.012	0.024	
θ	0°	8°	0°	8°	

NOTE:

Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.



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